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Product / Process Change Notification (PCN)

☐ Major change
☒ Minor change

PCN #:	PCN_IndMAIA_20210130	**Change Category:**
Affected Series:	WE-MAIA; 784383xxx	☐ Equipment / Location ☒ General Data ☐ Material ☐ Process ☐ Product Design ☐ Shipping / Packaging ☐ Supplier ☐ Software
PCN Date:	October 30, 2020	
Effective Date:	January 30, 2021	
Contact:	Product Management	**Data Sheet Change:**
Phone:	+49 (0) 7942 - 945 5001	☒ Yes ☐ No
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DESCRIPTION AND PURPOSE OF CHANGE:

To improve the processability, Würth Elektronik will add a recommendation on the solder paste thickness.

This is only a datasheet amendment, there will be no change in form, fit, function, quality or reliability of the product.

DETAIL OF CHANGE:

The recommendation as follows:

“**Make sure that you use the correct thickness of solder paste to avoid an insufficient soldering result. We recommend 100µm solder paste as a reference.**”

Will be implemented under the Classification Soldering Profile and in the Cautions and Warnings.

The drafts below show the parts of the datasheet in question:

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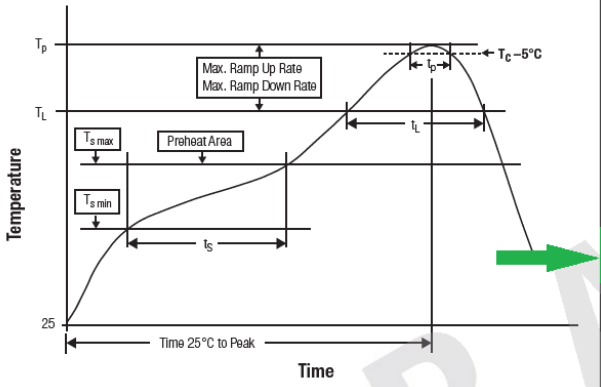
Classification Reflow Profile for SMT components:



Classification Reflow Soldering Profile:

Profile Feature		Value
Preheat Temperature Min	$T_{s\,min}$	150 °C
Preheat Temperature Max	$T_{s\,max}$	200 °C
Preheat Time t_s from $T_{s\,min}$ to $T_{s\,max}$	t_s	60 - 120 seconds
Ramp-up Rate (T_L to T_P)		3 °C/ second max.
Liquidous Temperature	T_L	217 °C
Time t_L maintained above T_L	t_L	60 - 150 seconds
Peak package body temperature	T_p	$T_p \leq T_c$, see Table below
Time within 5°C of actual peak temperature	t_p	20 - 30 seconds
Ramp-down Rate (T_P to T_L)		6 °C/ second max.
Time 25°C to peak temperature		8 minutes max.

refer to IPC/ JEDEC J-STD-020E
Make sure that you use the correct thickness of solder paste to avoid an insufficient soldering result. We recommend 100µm solder paste as a reference.

Package Classification Reflow Temperature (T_c):

Properties	Volume mm³ <350	Volume mm³ 350-2000	Volume mm³ >2000
PB-Free Assembly I Package Thickness < 1.6 mm	260 °C	260 °C	260 °C
PB-Free Assembly I Package Thickness 1.6 mm - 2.5 mm	260 °C	250 °C	245 °C
PB-Free Assembly I Package Thickness ≥ 2.5 mm	250 °C	245 °C	245 °C

refer to IPC/ JEDEC J-STD-020E

Cautions and Warnings:

The following conditions apply to all goods within the product series of WE-MAIA of Würth Elektronik eiSos GmbH & Co. KG:

General:

- This electronic component is designed and manufactured for use in general electronic equipment.
- Würth Elektronik must be asked for written approval (following the PPAP procedure) before incorporating the components into any equipment in fields such as military, aerospace, aviation, nuclear control, submarine, transportation (automotive control, train control, ship control), transportation signal, disaster prevention, medical, public information network, etc. where higher safety and reliability are especially required and/or if there is the possibility of direct damage or human injury.
- Electronic components that will be used in safety-critical or high-reliability applications, should be pre-evaluated by the customer.
- The component is designed and manufactured to be used within the datasheet specified values. If the usage and operation conditions specified in the datasheet are not met, the wire insulation may be damaged or dissolved.
- Do not drop or impact the components, the component may be damaged.
- Würth Elektronik products are qualified according to international standards, which are listed in each product reliability report. Würth Elektronik does not warrant any customer qualified product characteristics beyond Würth Elektroniks' specifications, for its validity and sustainability over time.
- The responsibility for the applicability of the customer specific products and use in a particular customer design is always within the authority of the customer. All technical specifications for standard products also apply to customer specific products.

Product specific:

Soldering:

- The solder profile must comply with the technical product specifications. All other profiles will void the warranty.
- All other soldering methods are at the customers' own risk.
- To improve the solderability of bottom termination components please refer to appnote ANP036 on our homepage.
- Make sure that you use the correct thickness of solder paste to avoid an insufficient soldering result. We recommend 100µm solder paste as a reference.

Cleaning and Washing:

- Washing agents used during the production to clean the customer application might damage or change the characteristics of the wire insulation, marking or plating. Washing agents may have a negative effect on the long-term functionality of the product.

Potting:

- If the product is potted in the customer application, the potting material might shrink or expand during and after hardening. Shrinking could lead to an incomplete seal, allowing contaminants into the core. Expansion could damage the components. We recommend a manual inspection after potting to avoid these effects.

Storage Conditions:

- A storage of Würth Elektronik products for longer than 12 months is not recommended. Within other effects, the terminals may suffer degradation, resulting in bad solderability. Therefore, all products shall be used within the period of 12 months based on the day of shipment.
- Do not expose the components to direct sunlight.
- The storage conditions in the original packaging are defined according to DIN EN 61760-2.
- The storage conditions stated in the original packaging apply to the storage time and not to the transportation time of the components.

Handling:

- Violation of the technical product specifications such as exceeding the nominal rated current will void the warranty.
- Applying currents with audio-frequency signals may result in audible noise due to the magnetostrictive material properties.
- The temperature rise of the component must be taken into consideration. The operating temperature is comprised of ambient temperature and temperature rise of the component. The operating temperature of the component shall not exceed the maximum temperature specified.

These cautions and warnings comply with the state of the scientific and technical knowledge and are believed to be accurate and reliable. However, no responsibility is assumed for inaccuracies or incompleteness.

RELIABILITY / QUALIFICATION SUMMARY:

Solderability / J-STD-002

Vibration / MIL-STD 202G Method 204